

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L8	52	((leadframe lead adj frame lead\$3frame) and lamin\$5 and (chip die ic integrated adj circuit) and pack\$3).clm.	US-PGPUB	OR	ON	2008/06/06 16:21
S416	4	("20020017718" "6313529").PN. OR ("6635962").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S415	338	S414 and lead near1 frame and (solder near2 ball bump c4 flip)	USPAT	OR	ON	2008/06/06 12:15
S414	2350	(257/777).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	OFF	2008/06/06 12:15
S413	197	(plur\$5 multi) near2 (film layer laminat\$3) with frame and (IC semiconductor silicon integrated adj circuit chip die wafer)	EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S412	50	(plur\$5 multi) near2 (film layer laminat\$3) near2 frame and (IC semiconductor silicon integrated adj circuit chip die wafer)	EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S411	681	(plur\$5 multi) near2 (film layer laminat\$3) near2 frame and (IC semiconductor silicon integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S410	2329	(plur\$5 multi) near2 (film layer laminat\$3) with frame and (IC semiconductor silicon integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S409	0	("(plur\$5multi)near2(film layer laminat\$3)with frame and (IC semiconductor silicon integrated adj circuit chip die wafer)").PN.	FPFS; EPO; JPO; DERWENT; BM_TDB	OR	OFF	2008/06/06 12:15

S408	3	("6081031" "6555899" "6677672").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S407	1	"6734044".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S406	12	S404 and (solder adj) contact solder near ball bump c4)	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S405	152	S404 not S399	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S404	157	multi\$3layer near2 lead adj frame	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S403	4	("3784948" "3925801" "4627151").PN. OR ("6255141").UPPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S402	2	"6255141".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S401	242	S398 or S399	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S400	63	S398 and S399	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S399	162	S397 and 257/67\$1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15

S398	143	S397 and 257/66\$1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S397	1614	laminat\$3 with lead adj frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S396	142	("3784883" "4168507" "4541035" "4577214" "4595945" "4608592" "4639760" "4675717" "4680613" "4705917").PNL OR ("4891687").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S395	12	("3597834" "3848077" "4113981" "4925024" "5025114" "5180888" "5183969" "5262226").PNL OR ("5399809").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S394	56	S393 not S389	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S393	81	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium it tungsten w gold au) and lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S392	28	S390 not S389	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S391	38	S390 not "44"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15

S390	53	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) and lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S389	25	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) same lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S388	42	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S387	98	S386 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S386	239	S381 and "257"/\$.cls.	USPAT	OR	ON	2008/06/06 12:15
S385	98	S382 and "257"/\$.cls.	USPAT	OR	ON	2008/06/06 12:15
S384	149	S382 and "257"/\$.cls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S383	2671	(IC chip integrated near2 circuit die semiconductor) near S379 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15

S382	232	S381 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S381	2671	(IC chip integrated near2 circuit die semiconductor) near S379 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S380	2	S379 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S379	2	"6734044".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S378	2	"5196725".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S377	2	"5229647".pn.	USPAT; DERWENT	OR	ON	2008/06/06 12:15
S376	2	"5196725".pn.	USPAT; DERWENT	OR	ON	2008/06/06 12:15
S375	2	"5191725".pn.	USPAT; DERWENT	OR	ON	2008/06/06 12:15
S374	1	1992-386699.NPAN.	DERWENT	OR	ON	2008/06/06 12:15
S373	9	(US-5777265-\$ or US-5734198-\$ or US-5399809-\$ or US-5864173-\$ or US-5214845-\$ or US-4891687-\$ or US-5389816-\$).did. or (US-5777265-\$ or JP-04286148-\$).did.	USPAT; DERWENT	OR	ON	2008/06/06 12:15

S372	37	"4445271" "4835120" "4891687" "5032895" "5053921" "5089878" "5089881").PN. OR ("5220195").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S371	6	("4891687" "5089878" "5196725" "5214845" "5220195" "5237202").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S370	9	("4891687" "5089878" "5196725" "5214845" "5220195" "5237202").PN. OR ("5389816").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S369	26	(Multi near2 layer with lead near2 frame).ti. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S368	25	"4320438" "4839717" "4879588" "4891687" "4972253" "4980034" "5008734" "5012386" "5158912" "5235209" "5235211" "5258575" "5264729" "5272590" "5311057" "5331511").PN. OR ("5777285").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S367	10	"5,196,725", "5,237,202", "5,399,809", "5,734,198" "5,777,265").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S366	483	S365 and (multi near2 layer multilayer laminate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S365	4648	(257/666).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/06 12:15
S364	3	("6081031" "6555899" "6677672").PN. OR ("6734044").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S363	2	"6734044".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S362	3	("6081031" "6555899" "6677672").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S361	1	"6734044".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15

S360	12	S358 and (solder adj) contact solder near ball bump c4)	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S359	152	S358 not S353	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S358	157	multi\$3layer near2 lead adj frame	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S357	4	("3784948" "3925801" "4627151").PN. OR ("6255141").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S356	2	"6255141".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S355	242	S352 or S353	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S354	63	S352 and S353	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S353	162	S351 and 257/67\$1.cds.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S352	143	S351 and 257/66\$1.cds.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15

S351	1614	laminat\$3 with lead adj frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S350	142	("3784883" "4168507" "4541035" "4577214" "4595945" "4608592" "4639760" "4675717" "4680613" "4705917").PN. OR ("4891687").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S349	12	("3597834" "3848077" "4113981" "4925024" "5025114" "5180888" "5183969" "5262226").PN. OR ("5399809").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S348	56	S347 not S343	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S347	81	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium il tungsten w gold au) and lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S346	28	S344 not S343	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S345	38	S344 not "44"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S344	53	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) and lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15

S343	25	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) same lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S342	42	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S341	98	S340 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S340	239	S335 and "257"/\$.cls.	USPAT	OR	ON	2008/06/06 12:15
S339	98	S337 and "257"/\$.cls.	USPAT	OR	ON	2008/06/06 12:15
S338	149	S337 and "257"/\$.cls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S337	232	S335 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S336	2	S334 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15

S335	2671	(IC chip integrated near2 circuit die semiconductor) near S334 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S334	2	"6734044".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S333	2	"5196725".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S332	2	"5229647".pn.	USPAT; DERWENT	OR	ON	2008/06/06 12:15
S331	2	"5196725".pn.	USPAT; DERWENT	OR	ON	2008/06/06 12:15
S330	2	"5191725".pn.	USPAT; DERWENT	OR	ON	2008/06/06 12:15
S329	1	1992-386699.NFAN.	DERWENT	OR	ON	2008/06/06 12:15
S328	9	(US-5777265-\$ or US-5734198-\$ or US-5399809-\$ or US-5864173-\$ or US-5214845-\$ or US-4891687-\$ or US-5389816-\$).did. or (US-5777265-\$ or JP-04286148-\$).did.	USPAT; DERWENT	OR	ON	2008/06/06 12:15
S327	37	("4445271" "4835120" "4891687" "5032895" "5053921" "5089878" "5089881").PN. OR ("5220195").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S326	6	("4891687" "5089878" "5196725" "5214845" "5220195" "5237202").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S325	9	("4891687" "5089878" "5196725" "5214845" "5220195" "5237202").PN. OR ("5389816").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S324	26	(Multi near2 layer with lead near2 frame).ti. and "257"/\$.ocls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S323	25	("4320438" "4839717" "4879588" "4891687" "4972253" "4980034" "5008734" "5012386" "5158912" "5235209" "5235211" "5258575" "5264729" "5272590" "5311057" "5331511").PN. OR ("5777265").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15

S322	10	("5,196,725", "5,237,202", "5,399,809", "5,734,198" "5,777,265").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S321	483	S320 and (multi near2 layer multilayer laminate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S320	4648	(257/666).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	OFF	2008/06/06 12:15
S319	3	("6081031" "6555899" "6677672").PN. OR ("6734044").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S318	2	"6734044".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S317	18	("5578525" "5580795" "5909058" "6188127" "6204562" "6287892" "6324067" "6350954").PN. OR ("6548330").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S316	13	("3908185" "4866571" "5057376" "5404273" "5689091" "5801446" "5847936" "5936305" "6011692").PN. OR ("6350954").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S315	172	S314 and cavity	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S314	578	S312 and S313	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S313	662	(lead near1 frame or leadframe) with (multilayer\$3 or multi near1 layer\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S312	20630	(lead near1 frame or leadframe).bstx.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S311	17	("20020020907" "20020031856" "5243498" "5629563" "6143981" "6236109" "6284570" "6369454" "6458617" "6507098").PN. OR ("6677672").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15

S310	3	("6081031" "6555899" "6677672").PN. OR ("6734044").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S309	3	("6081031" "6555899" "6677672").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S308	3	("6081031" "6555899" "6677672").PN. OR ("6734044").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S307	4	("20020017718" "6313529").PN. OR ("6635962").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S306	338	S305 and lead near1 frame and (solder near2 ball bump o4 flip)	USPAT	OR	ON	2008/06/06 12:15
S305	2350	(257/777).CCL.S.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/06 12:15
S304	197	(plur\$5 multi) near2 (film layer laminat\$3) with frame and (IC semiconductor silicon integrated adj circuit chip die wafer)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S303	50	(plur\$5 multi) near2 (film layer laminat\$3) near2 frame and (IC semiconductor silicon integrated adj circuit chip die wafer)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S302	681	(plur\$5 multi) near2 (film layer laminat\$3) near2 frame and (IC semiconductor silicon integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S301	2329	(plur\$5 multi) near2 (film layer laminat\$3) with frame and (IC semiconductor silicon integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S300	0	("(plur\$5 multi) near2 (film layer laminat\$3) with frame and (IC semiconductor silicon integrated adj circuit chip die wafer)").PN.	FPFS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/06 12:15
S299	3	("6081031" "6555899" "6677672").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15

S298	1	"6734044".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S297	12	S295 and (solder adj) contact solder near ball bump 04)	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S296	152	S295 not S290	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S295	157	multi\$3layer near2 lead adj frame	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S294	4	("3784948" "3925801" "4627151").PN. OR ("6255141").UPPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S293	2	"6255141".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S292	242	S289 or S290	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S291	63	S289 and S290	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S290	162	S288 and 257/67\$1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S289	143	S288 and 257/66\$1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15

S288	1614	laminat\$3 with lead adj frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S287	142	("3784883" "4168507" "4541035" "4577214" "4595945" "4608592" "4639760" "4675717" "4680613" "4705917").PN. OR ("4891687").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S286	12	("3597834" "3848077" "4113981" "4925024" "5025114" "5180888" "5183969" "5262226").PN. OR ("5399809").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S285	56	S284 not S280	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S284	81	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium il tungsten w gold au) and lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S283	28	S281 not S280	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S282	38	S281 not "44"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S281	53	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) and lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15

S280	25	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) same lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S279	42	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S278	98	S277 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S277	239	S272 and "257"/\$.cls.	USPAT	OR	ON	2008/06/06 12:15
S276	98	S273 and "257"/\$.cls.	USPAT	OR	ON	2008/06/06 12:15
S275	149	S273 and "257"/\$.cls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S274	2671	(IC chip integrated near2 circuit die semiconductor) near S270 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S273	232	S272 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15

S272	2671	(IC chip integrated near2 circuit die semiconductor) near S270 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S271	2	S270 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S270	2	"6734044".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S269	2	"5196725".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S268	2	"5229647".pn.	USPAT; DERWENT	OR	ON	2008/06/06 12:15
S267	2	"5196725".pn.	USPAT; DERWENT	OR	ON	2008/06/06 12:15
S266	2	"5191725".pn.	USPAT; DERWENT	OR	ON	2008/06/06 12:15
S265	1	1992-386699.NPAN.	DERWENT	OR	ON	2008/06/06 12:15
S264	9	(US-5777265-\$ or US-5734198-\$ or US-5399809-\$ or US-5864173-\$ or US-5214845-\$ or US-4891687-\$ or US-5389816-\$).did. or (US-5777265-\$ or JP-04286148-\$).did.	USPAT; DERWENT	OR	ON	2008/06/06 12:15
S263	37	("4445271" "4835120" "4891687" "5032895" "5053921" "5089878" "5089881").PN. OR ("5220195").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S262	6	("4891687" "5089878" "5196725" "5214845" "5220195" "5237202").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S261	9	("4891687" "5089878" "5196725" "5214845" "5220195" "5237202").PN. OR ("5389816").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15

S260	26	(Multi near2 layer with lead near2 frame).ti. and "257"/\$.ccis.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S259	25	("4320438" "4839717" "4879588" "4891687" "4972253" "4980034" "5008734" "5012386" "5158912" "5235209" "5235211" "5258575" "5264729" "5272590" "5311057" "5331511").PN. OR ("5777265").UPPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S258	10	("5,196,725", "5,237,202", "5,399,809", "5,734,198" "5,777,265").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S257	483	S256 and (multi near2 layer multilayer laminate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S256	4648	(257/666).CCIS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	OFF	2008/06/06 12:15
S255	3	("6081031" "6555899" "6677672").PN. OR ("6734044").UPPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S254	2	"6734044".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S253	3	("6081031" "6555899" "6677672").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S252	1	"6734044".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S251	12	S249 and (solder adj) contact solder near ball bump c4)	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S250	152	S249 not S244	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S249	157	multi\$3layer near2 lead adj frame	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15

S248	4	("3784948" "3925801" "4627151").PN. OR ("6255141").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S247	2	"6255141".pn.	US-PGPUB; USPAT; USOCR; EPC; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S246	242	S243 or S244	US-PGPUB; USPAT; USOCR; EPC; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S245	63	S243 and S244	US-PGPUB; USPAT; USOCR; EPC; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S244	162	S242 and 257/67\$1.ccls.	US-PGPUB; USPAT; USOCR; EPC; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S243	143	S242 and 257/66\$1.ccls.	US-PGPUB; USPAT; USOCR; EPC; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S242	1614	laminat\$3 with lead adj frame	US-PGPUB; USPAT; USOCR; EPC; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S241	142	("3784883" "4168507" "4541035" "4577214" "4595945" "4608592" "4639760" "4675717" "4680613" "4705917").PN. OR ("4891687").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S240	12	("3597834" "3848077" "4113981" "4925024" "5025114" "5180888" "5183969" "5262226").PN. OR ("5399809").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15

S239	56	S238 not S234	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S238	51	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten w gold au) and lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S237	28	S235 not S234	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S236	38	S235 not "44"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S235	53	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) and lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S234	25	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) same lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S233	42	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15

S232	98	S231 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S231	239	S226 and "257"/\$.cols.	USPAT	OR	ON	2008/06/06 12:15
S230	98	S228 and "257"/\$.cols.	USPAT	OR	ON	2008/06/06 12:15
S229	149	S228 and "257"/\$.cols.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S228	232	S226 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S227	2	S225 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S226	2671	(IC chip integrated near2 circuit die semiconductor) near S225 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15
S225	2	"6734044".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/06 12:15

S224	2	"5196725".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S223	2	"5229647".pn.	USPAT; DERWENT	OR	ON	2008/06/06 12:15
S222	2	"5196725".pn.	USPAT; DERWENT	OR	ON	2008/06/06 12:15
S221	2	"5191725".pn.	USPAT; DERWENT	OR	ON	2008/06/06 12:15
S220	1	1992-386699.NP.N.	DERWENT	OR	ON	2008/06/06 12:15
S219	9	(US-5777265-\$ or US-5734198-\$ or US-5399809-\$ or US-5864173-\$ or US-5214845-\$ or US-4891687-\$ or US-5389816-\$).did. or (US-5777265-\$ or JP-04286148-\$).did.	USPAT; DERWENT	OR	ON	2008/06/06 12:15
S218	37	("4445271" "4835120" "4891687" "5032895" "5053921" "5089878" "5089881").PN. OR ("5220195").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S217	6	("4891687" "5089878" "5196725" "5214845" "5220195" "5237202").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S216	9	("4891687" "5089878" "5196725" "5214845" "5220195" "5237202").PN. OR ("5389816").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S215	26	(Multi near2 layer with lead near2 frame).ti. and "257"/\$.ocls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S214	25	("4320438" "4839717" "4879588" "4891687" "4972253" "4980034" "5008734" "5012386" "5158912" "5235209" "5235211" "5258575" "5264729" "5272590" "5311057" "5331511").PN. OR ("5777265").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S213	10	("5,196,725", "5,237,202", "5,399,809", "5,734,198" "5,777,265").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15
S212	483	S211 and (multi near2 layer multilayer laminate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15

S211	4648	(257/666).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	OFF	2008/06/06 12:15
S210	3	("6081031" "6555899" "6677672").PN. OR ("6734044").UPPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/06/06 12:15
S209	2	"6734044".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/06/06 12:15

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